

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16574
1.3 Title of PCN	HTXA subcontractor (China) additional back-end qualification for 2Kb to 128Kb I ² C EEPROM in DFN8
1.4 Product Category	2Kb to 128Kb CMOSF8H+ I ² C EEPROM in DFN8
1.5 Issue date	2026-09-06

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	David RICETTO
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Transfer from one site to another site: Warehouse, hub including electronic data transfer (Inkless maps, PT data, STDF...), (SOP 2617)	NA

4. Description of change

	Old	New
4.1 Description	The low densities EEPROM I ² C 2Kb to 128Kb in DFN8 (CMOS F8H+ process technology) currently assembled & tested at ST Calamba (Philippines)...	...will also be assembled & tested at HTXA subcontractor (China).
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: Marking change - Fit: No change - Function: No change	

5. Reason / motivation for change

5.1 Motivation	The strategy of STMicroelectronics Connected Security division is to support our customers on products and service quality on a long-term basis. In line with this commitment, the qualification of the HTXA back-end assembly & test site as a second source will allow us to increase capacity and reinforce long term competitiveness.
5.2 Customer Benefit	DOUBLE SOURCING

6. Marking of parts / traceability of change

6.1 Description	Assembly plant identifier "U" on DFN8 package.
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7. Timing / schedule

7.1 Date of qualification results	2026-10-19
7.2 Intended start of delivery	2026-11-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	16574 Preliminary Reliability Report RRCS2610 - F8HP4 DFN8 HTXA.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-09-06

9. Attachments (additional documentations)
16574 Public product.pdf 16574 PCN DFN8 @HTXA.pdf 16574 Preliminary Reliability Report RRCS2610 - F8HP4 DFN8 HTXA.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-BFMC6TG	
	M24C02-FMC6TG	
	M24C02-RMC6TG	
	M24C04-FMC6TG	
	M24C04-RMC6TG	
	M24C08-FMC6TG	
	M24C08-RMC6TG	
	M24C16-FMC6TG	
	M24C16-RMC6TG	
	M24C32-FMC6TG	
	M24C64-FMC6TG	

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